

Product Change Notification / LIAL-09VUUA424

Date:

15-Jun-2022

Product Category:

Ethernet Controllers, Ethernet PHYs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5151 Initial Notice: Qualification of a new lead frame DAP surface prep material for selected KSZ8041xx, SPNZ80105xx and KSZ8851xx device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

Affected CPNs:

LIAL-09VUUA424_Affected_CPN_06152022.pdf LIAL-09VUUA424_Affected_CPN_06152022.csv

Notification Text:

PCN Status:Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of a new lead frame DAP surface prep material for selected KSZ8041xx, SPNZ80105xx and KSZ8851xx device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Microchip Technology Thailand	Microchip Technology Thailand				
	(HQ) (MTAI)	(HQ) (MTAI)				
Wire Material	Au/2N	Au/2N				
Die Attach Material	3280	3280				
Molding Compound Material	G700LTD	G700LTD				
Lead-Frame Material	A194	A194				
Lead Frame DAP Surface	Ag selective plating	Ag selective plating (Add more Ag area)				
Prep	See Pre and Post Change Summary for comparison.					

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change: To improve productivity by qualifying a new lead frame DAP surface prep material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: July 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	June 2022				July 2022					
Workweek	2 3	2 4	2 5	2 6	2 7	2 8	2 9	3 0	3 1	
Initial PCN Issue Date			х							
Qual Report					Х					

Availability					
Final PCN Issue Date			х		

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: June 15, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-09VUUA424_Pre and Post Change Summary.pdf PCN_LIAL-09VUUA424_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. LIAL-09VUUA424 - CCB 5151 Initial Notice: Qualification of a new lead frame DAP surface prep material for selected KSZ8041xx, SPNZ80105xx and KSZ8851xx device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

KSZ8041NL KSZ8041RNL SPNZ801059 KSZ8041NLI KSZ8041NL-TR KSZ8041NL-TR SPNZ801059-TR KSZ8041NLI-TR KSZ8041NLI-TR KSZ8041RNLI-TR KSZ8851SNL KSZ8851SNLI KSZ8851SNLI-TR